Unit: mm

2SC2497, 2SC2497A

Silicon NPN epitaxial planar type

For low-frequency power amplification Complementary to 2SA1096 and 2SA1096A

Features

- High collector to emitter voltage V_{CEO}
- TO-126B package which requires no insulation plate for installation to the heat sink

Absolute Maximum F	ratings 1 _C	= 25°C		.
Parameter	Symbol	Rating	Unit	<u>0.75±</u>
Collector to base voltage	V _{CBO}	70	V	
Collector to 2SC2497	V _{CEO}	50	V	
emitter voltage 2SC2497A		60		
Emitter to base voltage	V _{EBO}	5	V	4.4
Peak collector current	I _{CP}	3	А	2 12
Collector current	I _C	1.5	A	3
Collector power dissipation	P _C	1.2 *1	W	~O'
		5 *2		
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	-



8.0+0.5 3.2±0.2 11.0±0.5 **3.8±0.3** 3.05±0.1 0+6 9 6.0+1 0.5±0.1 0.5±0.1 1.76±0.1 2.3±0.2 1 : Emitter 3 2 : Collector 3 : Base TO-126B-A1 Package

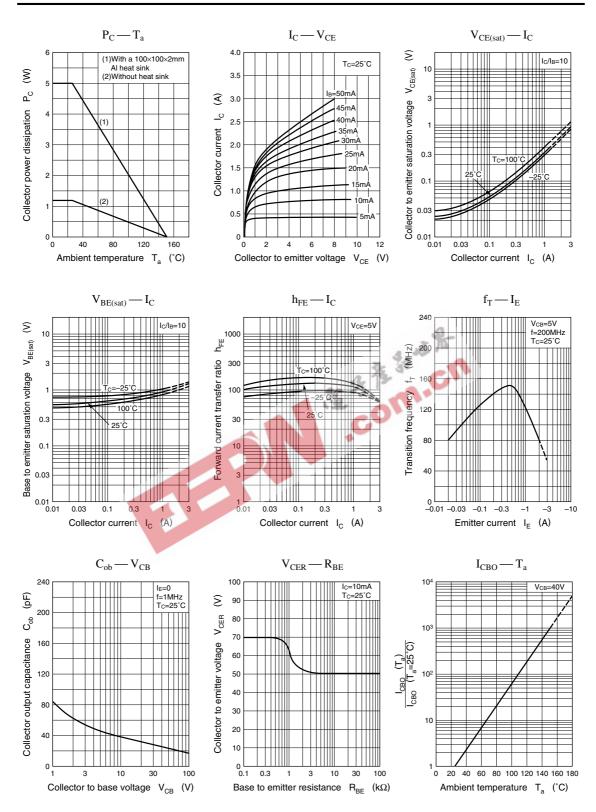
*2: With a $100 \times 100 \times 2$ mm A1 heat sink

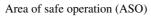
Electrical Characteristics $T_C = 25^{\circ}C$

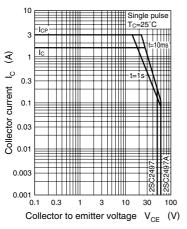
Parameter		Symbol	Conditions	Min	Тур	Мах	Unit
Collector cutoff current	İ	I _{CBO}	$V_{CB} = 20 \text{ V}, I_E = 0$			1	μA
		I _{CEO}	$V_{CE} = 10 \text{ V}, I_B = 0$			100	μA
Emitter cutoff current		I _{EBO}	$V_{EB} = 5 V, I_C = 0$			10	μΑ
Collector to base voltage	ge	V _{CBO}	$I_{\rm C} = 1 {\rm mA}, I_{\rm E} = 0$	70			V
Collector to emitter	2SC2497	V _{CEO}	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
voltage	2SC2497A			60			
Forward current transfe	r ratio *	h _{FE}	$V_{CE} = 5 V, I_C = 1 A$	80		220	
Collector to emitter satur	ration voltage	V _{CE(sat)}	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 0.15 \text{ A}$			1	V
Base to emitter saturation	on voltage	V _{BE(sat)}	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 0.15 \text{ A}$			1.5	V
Transition frequency		f_T	$V_{CB} = 5 V, I_E = -0.5 A, f = 200 MHz$		150		MHz
Collector output capaci	tance	C _{ob}	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		35		pF

Note) *: Rank classification

Rank	R	S		
\mathbf{h}_{FE}	80 to 160	120 to 220		









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